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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

First Named Inventor: Yoshiaki TANAKA §
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Conf. No.: Not Yet Assigned § Group Art Unit: Not Yet Assigned
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Appln. No.: Not Yet Assigned § Examiner: Not Yet Assigned
§
Filing Date: Herewith § Attorney Docket No.: 10844-35US
§ (203070(D-2))
Title: ALLOY TYPE THERMAL FUSE AND MATERIAL FOR A THERMAL FUSE
ELEMENT

INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §1.97(b)

Enclosed are copies of each of the documents listed on the attached Information Disclosure Citation Form(s) PTO/SB/08A and/or B, which may be material to the patentability of this application and/or for which there may be a duty to disclose in accordance with 37 C.F.R. §1.56.

The following comments summarize the cited references. Conventionally, the following thermal fuses which have an alloy composition of Bi-In-Sn, and which satisfy the requirement of an operating temperature of 75 to 120°C are known: a thermal fuse in which a fuse element has an alloy composition of 47 to 49% Sn, 51 to 53% In, and an adequate amount of Bi, and which has an operating temperature of 105 to 115°C (Japanese Patent Application Laying-Open No. 56-114237); that in which a fuse element has an alloy composition of 42 to 53% In, 40 to 46% Sn, and 7 to 12 % Bi, and which has an operating temperature of 95 to 105°C (Japanese Patent Application Laying-Open No. 2001-266724); that in which a fuse element has an alloy composition of 51 to 53% In, 42 to 44% Sn, and 4 to 6% Bi, and which has an operating temperature of 107 to 113°C (Japanese Patent Application Laying-Open No. 59-8229); that in which a fuse element has an alloy composition of 1 to 15% Sn, 20 to 33% Bi, and the balance In, and which has an operating temperature of 75 to 100°C (Japanese Patent Application Laying-Open No. 2001-325867); and that in which a fuse element has an alloy composition of 0.3 to 1.5% Sn, 51 to 54% In, and the balance Bi, and which has an operating temperature of 86 to

89°C (Japanese Patent Application Laying-Open No. 6-325670). Furthermore, a thermal fuse is known in which a fuse element has an alloy composition of a Bi-In system not containing Sn and of 45 to 55% Bi and the balance In, and which has an operating temperature of 85 to 95°C (Japanese Patent Application Laying-Open No. 2002-150906).

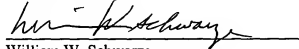
The filing of this Information Disclosure Statement shall not be construed as an admission that any of the listed documents constitutes prior art, nor as an admission against interest in any manner.

No fee is believed to be due in connection with the filing of this Information Disclosure Statement since it is being filed within three months of the filing date of the above-identified application. However, the Commissioner is hereby authorized to charge any deficiencies or credit any overpayments to Deposit Account No. 50-1017.

It is respectfully requested that this Information Disclosure Statement and the documents listed on the attached Form PTO/SB/08A and/or B be considered and acknowledged by the Examiner in connection with the above-identified patent application, be made of record therein, and that the listed document(s) be cited in the issued patent.

Respectfully submitted,

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Enclosures

